

Yong Xiao

List of Publications by Year in descending order

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#	ARTICLE	IF	CITATIONS
1	Ultrasonic-assisted soldering for graphite films as heat sinks with durably superior heat dissipating efficiency. <i>Advanced Composites and Hybrid Materials</i> , 2022, 5, 2154-2162.	9.9	8
2	Ultrasonic brazing of Zr-based bulk metallic glass and 1060 Al alloy using Zn-3Al filler metal. <i>Journal of Advanced Joining Processes</i> , 2022, 5, 100095.	1.5	5
3	Microstructure evolution and interfacial bonding mechanisms of ultrasonically soldered sapphire/Al dissimilar joints using Sn-based solders. <i>Ceramics International</i> , 2022, 48, 20070-20077.	2.3	6
4	Effect of Ni foam addition on the microstructure and mechanical properties of In-48Sn eutectic alloy. <i>Journal of Materials Science: Materials in Electronics</i> , 2022, 33, 12594-12603.	1.1	2
5	Microstructure transformation and mechanical properties of Al alloy joints soldered with Ni-Cu foam/Sn-3.0Ag-0.5Cu (SAC305) composite solder. <i>Journal of Alloys and Compounds</i> , 2022, 922, 166135.	2.8	8
6	High Entropy Alloys as Filler Metals for Joining. <i>Entropy</i> , 2021, 23, 78.	1.1	19
7	Soldering of Graphene Assembled Films with Ultrasonic Assistance and Its Utilization Potentiality in Electronic Devices. , 2021, , .		0
8	Ultrasonic bonding of 2024 Al alloy using Ni-foam/Sn composite solder at ambient temperature. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2020, 771, 138663.	2.6	12
9	Rapid soldering of flexible graphene assembled films at low temperature in air with ultrasonic assistance. <i>Carbon</i> , 2020, 158, 55-62.	5.4	11
10	Diffusion reaction-induced microstructure and strength evolution of Cu joints bonded with Sn-based solder containing Ni-foam. <i>Materials Letters</i> , 2020, 281, 128642.	1.3	18
11	Cu interconnects soldered with a novel Sn-based composite solder reinforced by Ni-Cu alloy foam. , 2020, , .		0
12	Enhanced output performance of flexible piezoelectric energy harvester by using auxetic graphene films as electrodes. <i>Applied Physics Letters</i> , 2020, 117, .	1.5	10
13	Bonding and strengthening mechanism of ultrasonically soldered 7075 Al joint using Ni-foam/Sn composite solder foil. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2020, 791, 139691.	2.6	14
14	Microstructure and mechanical properties of Cu joints soldered with a Sn-based composite solder, reinforced by metal foam. <i>Journal of Alloys and Compounds</i> , 2020, 845, 156240.	2.8	36
15	Microstructure evolution and mechanical properties of Cu interconnects bonded with Ni-foam reinforced pure Sn solder. , 2019, , .		0
16	Dissimilar Cu/Al tube joint by EMF-assisted brazing. <i>International Journal of Advanced Manufacturing Technology</i> , 2018, 95, 4039-4047.	1.5	1
17	Ultrasonic soldering of Cu alloy using Ni-foam/Sn composite interlayer. <i>Ultrasonics Sonochemistry</i> , 2018, 45, 223-230.	3.8	29
18	Ultrasound-induced liquid/solid interfacial reaction between Zn-3Al alloy and Zr-based bulk metallic glasses. <i>Ultrasonics Sonochemistry</i> , 2018, 45, 86-94.	3.8	7

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19	Microstructure and mechanical properties of 7075-Al alloy joint ultrasonically soldered with Ni-foam/Sn composite solder. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2018, 729, 241-248.	2.6	25
20	Facile and highly efficient fabrication of robust Ag nanowire- <i>elastomer composite electrodes with tailored electrical properties.</i> <i>Journal of Materials Chemistry C</i> , 2018, 6, 7207-7218.	2.7	49
21	Interfacial reaction behavior and bonding mechanism between liquid Sn and ZrO ₂ ceramic exposed in ultrasonic waves. <i>Ceramics International</i> , 2017, 43, 7531-7536.	2.3	15
22	Ultrasound-assisted soldering of alumina using Ni-foam reinforced Sn-based composite solders. <i>Ceramics International</i> , 2017, 43, 14314-14320.	2.3	15
23	Ultrasound-assisted soldering of Cu alloy using a Ni-foam reinforced Sn composite solder. , 2017, , .		3
24	Interfacial reaction behavior and mechanical properties of ultrasonically brazed Cu/Zn- <i>Al/Cu joints.</i> <i>Materials & Design</i> , 2015, 73, 42-49.	5.1	47
25	Ultrasound-induced equiaxial flower-like CuZn ₅ /Al composite microstructure formation in Al/Zn- <i>Al/Cu joint.</i> <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2014, 594, 135-139.	2.6	29
26	Microstructure and joint properties of ultrasonically brazed Al alloy joints using a Zn- <i>Al hypereutectic filler metal.</i> <i>Materials & Design</i> , 2013, 47, 717-724.	5.1	36
27	Ultrasound-assisted brazing of Cu/Al dissimilar metals using a Zn- <i>3Al filler metal.</i> <i>Materials & Design</i> , 2013, 52, 740-747.	5.1	72
28	Rapid formation of Cu/Cu ₃ Sn/Cu joints using ultrasonic bonding process at ambient temperature. <i>Applied Physics Letters</i> , 2013, 102, .	1.5	68
29	Microstructure evolution and mechanical properties of ultrasonically soldered 7075 Al alloy joint with metal foam/Sn composite solder. <i>Welding in the World, Le Soudage Dans Le Monde</i> , 0, , .	1.3	1